

**LISTING OF THE CLAIMS:**

Claims 1-4 (Cancelled)

5. (Original) An interconnection wiring system containing at least one capacitor comprising:

a substrate having a planar upper surface of insulating and conductive regions therein,

a first level of interconnection wiring interconnecting said conductive regions,

a first dielectric layer formed over said first level of interconnection wiring,

said first dielectric layer having an upper surface and having vias therein filled with  
conductive material to said upper surface and in contact with regions of said first level of  
interconnection wiring,

at least one of said vias having dimensions to form said lower electrode of a capacitor,

a second dielectric layer formed over said lower electrode and extending beyond the perimeter  
of said lower electrode, and

a second level of interconnection wiring interconnecting the vias filled with conductive material and formed over the second dielectric layer to form said top electrode of said capacitor.

6. (Currently Amended) The interconnection wiring system, of claim + 5 wherein said lower electrode has an upper surface of titanium nitride.

7. (Currently Amended) The interconnection wiring system of claim + 5 wherein said top electrode has a lower surface of titanium nitride.

8. (Original) The interconnection wiring system of claim 6 wherein said top electrode has a lower surface of titanium nitride.

Claims 9-16 (Cancelled)